



PDA150F series Reliability test results

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| No. | Test Item | Testing conditions | Conditions of acceptability | Number of samples | Number of failures |
|-----|---|--|---|-------------------|--------------------|
| 1 | Heat cycle test | (1) -40°C ~ 125°C 30 minutes each (2) 800 cycles | (1)No degradation of electric characteristics after test. (2)No crack at solder joint. | 1 | 0 |
| 2 | High temperature/ High humidity bias test | (1) Ta=85°C, RH=85% (2) At rated input (3) Load 0% (4) 1000 hours | (1)No degradation of electric characteristics after test. | 1 | 0 |
| 3 | Vibration test | (1) f=10~150Hz, 29.4m/s ² (3G) (2) 3 minutes period (3) 60 minutes along X, Y and Z axis | (1)No degradation of electric characteristics after test. (2)No crack at solder joint. (3)No mechanical damage of appearance. | 3 | 0 |
| 4 | Impact test | (1) 294m/s ² (30G), 11ms (2) Once each X, Y and Z axis | (1)No degradation of electric characteristics after test. (2)No crack at solder joint. (3)No thermal damage of appearance. | 3 | 0 |
| 5 | Electrostatic discharge immunity test | (1) Ambient temperture 25±10°C (2) At rated input and load (3) Contact discharge : Level 4 (8kV) (4) Air discharge : Level 4 (15kV) (5) Applied to Input, Output, FG | (1)No protection circuit fail. (2)No output voltage drop with control circuit fail. (3)No function fail. | 1 | 0 |